

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	MDG/21/12540	
1.3 Title of PCN	Amkor ATP (Philippines) TSSOP20 package additional line for STM32G listed products	
1.4 Product Category	STM32G03 64K in TSSOP20 package	
1.5 Issue date	2021-04-26	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	KRISZTINA NEMETH
2.1.2 Phone	+49 89460062210
2.1.3 Email	krisztina.nemeth@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Ricardo Antonio DE SA EARP
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	AMKOR ATP (Philippines)

4. Description of change

	Old	New
4.1 Description	Back-End Source: - ST Shenzhen (China)	Back-End Source: - ST Shenzhen (China) - AMKOR ATP (Philippines) Added
4.2 Anticipated Impact on form, fit, function, quality, reliability or processability?	Lead color and surface finish will change due to different leadframe finishing. Pin1 identifier might change in terms of form and positioning. Package darkness changes depending on molding.	

5. Reason / motivation for change

5.1 Motivation	To sustain MCD microcontrollers success in the market, ST Microcontrollers Division must convert the line to maintain state of the art service level to our customers
5.2 Customer Benefit	CAPACITY INCREASE

6. Marking of parts / traceability of change

6.1 Description	Second level interconnect changes from e4 to e3. Tracability ensured by ST internal Tools.
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7. Timing / schedule

7.1 Date of qualification results	2021-04-08
7.2 Intended start of delivery	2021-05-14
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	12540 MDG-MCD-RER1712 V3.0 - PCN10233-PCN12540-ATP1 TSSOP20 XDLF for additional source - reliability evaluation report.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2021-04-26

9. Attachments (additional documentations)
12540 Public product.pdf 12540 MDG-MCD-RER1712 V3.0 - PCN10233-PCN12540-ATP1 TSSOP20 XDLF for additional source - reliability evaluation report.pdf 12540 PCN12540_Additional information.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32G030F6P6	
	STM32G031F4P6	
	STM32G031F6P6	
	STM32G031F8P6	
	STM32G030F6P6TR	

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